



ISO 1183

HOSTAFORM® M25AE

HOSTAFORM®

Hostaform® M25AE is a special grade of acetal copolymer targeted for extrusion shapes (rod, bar, plate, etc.) free of center porosity in large diameters and thicknesses.

Chemical abbreviation according to ISO 1043-1: POM

			4.5
Prod	LICT	intor	mation

Resin Identification	POM		ISO 1043
Part Marking Code	>POM<		ISO 11469
Rheological properties			
Melt volume-flow rate	25	cm ³ /10min	ISO 1133
Temperature	190		100 1100
Load	2.16	_	
Melt mass-flow rate		g/10min	ISO 1133
Melt mass-flow rate, Temperature	190		
Melt mass-flow rate, Load	2.16	kg	
Typical mechanical properties			
Tensile modulus	2400	MPa	ISO 527-1/-2
Tensile stress at yield, 50mm/min		MPa	ISO 527-1/-2
Tensile strain at yield, 50mm/min	11	%	ISO 527-1/-2
Flexural modulus		MPa	ISO 178
Charpy impact strength, 23°C	250 ^[P]	kJ/m²	ISO 179/1eU
Charpy impact strength, -30°C		kJ/m²	ISO 179/1eU
Charpy notched impact strength, 23°C		kJ/m²	ISO 179/1eA
Poisson's ratio	0.38 ^[C]		
[P]: Partial Break			
[C]: Calculated			
Thermal properties			
Melting temperature, 10 °C/min	163	°C	ISO 11357-1/-3
Temperature of deflection under load, 1.8 MPa	91	°C	ISO 75-1/-2
Coefficient of linear thermal expansion	110	E-6/K	ISO 11359-1/-2
(CLTE), parallel			
Coefficient of linear thermal expansion (CLTE),	100	E-6/K	ISO 11359-1/-2
normal			
Flammability			
FMVSS Class	В		ISO 3795 (FMVSS 302)
Burning rate, Thickness 1 mm	36.5	mm/min	ISO 3795 (FMVSS 302)
Physical/Other properties			
Humidity absorption, 2mm	0.2		Sim. to ISO 62

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1410 kg/m³

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Density





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Injection

Drying Recommended	no	
Drying Temperature	100	°C
Drying Time, Dehumidified Dryer	3 - 4	h
Processing Moisture Content	≤0.2	%
Melt Temperature Optimum	200	°C
Min. melt temperature	190	°C
Max. melt temperature	210	°C
Screw tangential speed	≤0.3	m/s
Mold Temperature Optimum	100	°C
Min. mould temperature	80	°C
Max. mould temperature	120	°C
Hold pressure range	60 - 120	MPa
Back pressure	4	MPa

Characteristics

Processing Injection Moulding, Extrusion, Sheet Extrusion, Other Extrusion

Delivery form Pellets

Additional information

Profile extrusion

Preprocessing

General drying is not necessary due to low moisture absorption of the resin.

In case of bad storage conditions (water contact or condensed water) the use of a recirculating air dryer (100 to 120 $^{\circ}$ C / max. 40 mm layer / 3 to 6 hours) is recommended.

Max. Water content 0,2 %

Processing

Standard extruders with grooved feed zone and short compression screws (minimum 25 D) will fit.

Melt temperature 180-190 °C

Postprocessing

Conditioning e.g. moisturizing is not necessary.

In case of very thick wall thickness profiles after-annealing it is recommended to reduce internal stress.

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Annealing temperature 130-140 °C Annealing time 10 min/mm thickness

Sheet extrusion

Preprocessing

General drying is not necessary due to low moisture absorption of the resin.

In case of bad storage conditions (water contact or condensed water) the use of a recirculating air dryer (100 to 120 $^{\circ}$ C / max. 40 mm layer / 3 to 6 hours) is recommended.

Max. Water content 0,2 %

Processing

Standard extruders with grooved feed zone and short compression screws (minimum 25 D) will fit.

Melt temperature 180-190 °C

Postprocessing

Conditioning e.g. moisturizing is not necessary.

In case of very thick wall thickness profiles after-annealing it is recommended to reduce internal stress.

Annealing temperature 130-140 °C Annealing time 10 min/mm thickness

Processing Notes

Pre-Drying

Drying is not normally required. If material has come in contact with moisture through improper storage or handling or through regrind use, drying may be necessary to prevent splay and odor problems.

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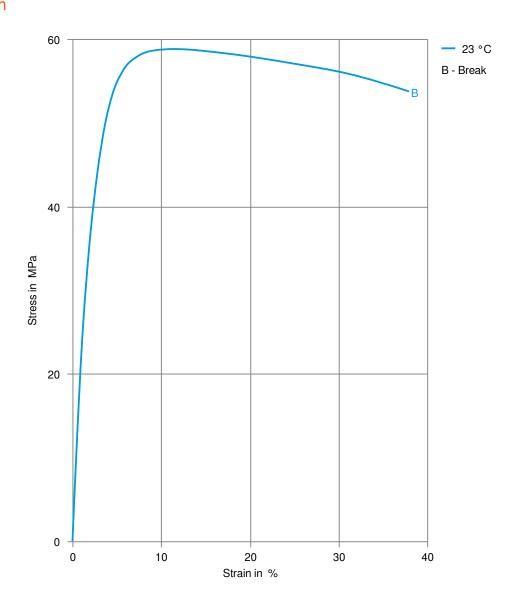




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Stress-strain



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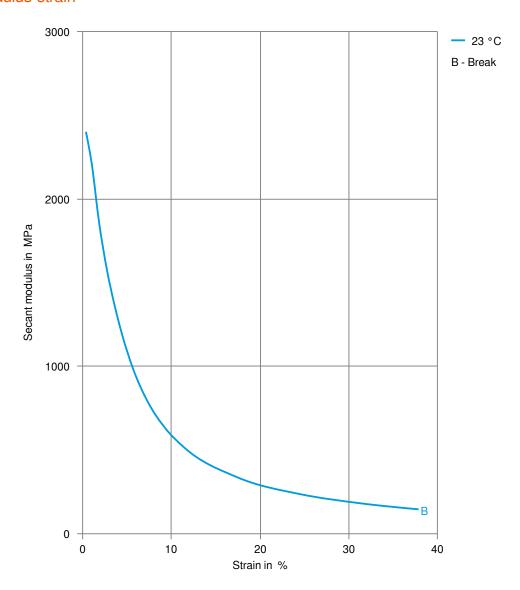
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Secant modulus-strain



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